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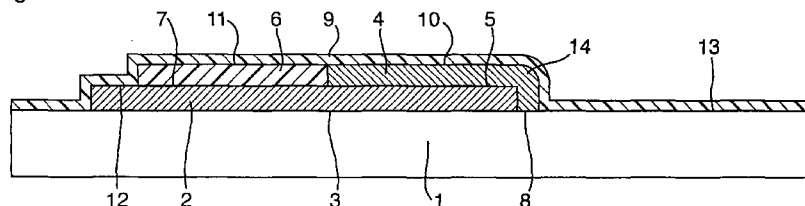
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(54) Title: METHOD FOR REDUCING CREEP CORROSION

Figure 13



(57) Abstract: A method for reducing creep corrosion on a printed circuit board, the printed circuit board comprising a substrate, a plurality of electrically conductive tracks located on at least one surface of the substrate, a solder mask coating at least a first area of the plurality of electrically conductive tracks and a surface finish coating at least a second area of the plurality of electrically conductive tracks, the method comprising depositing by plasma-polymerization a fluorohydrocarbon onto at least part of the solder mask and at least part of the surface finish.

